



SINGLE-CHANNEL SMART LOAD SWITCH

Description

The DML1012ALDSQ is a single-channel load switch with very low on-resistance in a small package. It contains an n-channel MOSFET for up to V_{BIAS} - 1.5V input-voltage operation and 6A current channel with 3.2V to 5.5V bias supply. The load switch is controlled by a lowvoltage control signal through ON pin.

Applications

- Portable electronics and systems
- Notebooks and tablet computers
- Telecoms, networking, medicals, and industrial equipment
- Set-top boxes, servers, and gateways

Features and Benefits

- Low RDS(ON) Ensures On-State Losses Are Minimized
- 0.8V to VBIAS 1.5V Input-Voltage Range
- 6A Continuous Current
- Low RDS(ON) Internal NFETs $8m\Omega$ at $V_{BIAS} = 5V$, $V_{IN} = 1.05V$, $T_A = +85$ °C
- 28µA Low Quiescent Current
- 20µs Turn-On Rise Time
- 3.2V to 5.5V Bias Voltage
- Integrated Quick Output Discharge Resistor
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DML1012ALDSQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

https://www.diodes.com/quality/product-definitions/

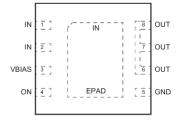
Mechanical Data

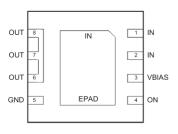
- Package: V-DFN3030-8
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @4)
- Weight: 0.022 grams (Approximate)











Top View

Bottom View

Top View

Bottom View

Ordering Information (Note 4)

Orderable Part Number	Part Number Package		Tono Ditoh	Packing		
Orderable Part Number	Package	Tape Width	Tape Pitch	Qty.	Carrier	
DML1012ALDSQ-7A	V-DFN3030-8 (Type R)	12mm	8mm	1,500	Tape & Reel	
DML1012ALDSQ-13	V-DFN3030-8 (Type R)	12mm	8mm	3,000	Tape & Reel	

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



Marking Information

Site 1

V-DFN3030-8 (Type R)



LS2A = Product Type Marking Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 25 = 2025) WW = Week Code (01 to 53)

Site 2

V-DFN3030-8 (Type R)

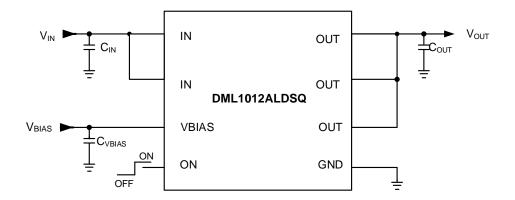


LS2A = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 5 = 2025) W = Week (ex: a = Week 27; z Represents Week 52 and 53) X = Internal Code (ex: U = Monday)

Date Code Key

Date Code Rey												
Year	2025	2026	2027	2028	2029	2030	2031	2032	2033	2034	2035	2036
Code	5	6	7	8	9	0	1	2	3	4	5	6
Week	1-26			27-52			53					
Code	A-Z				a-z			z				
Internal Code	Sun	1	Mon		Tue	W	ed	Thu		Fri		Sat
Cada	Т		11	i i	17	1	.,	V		V	İ	7

Typical Application Circuit

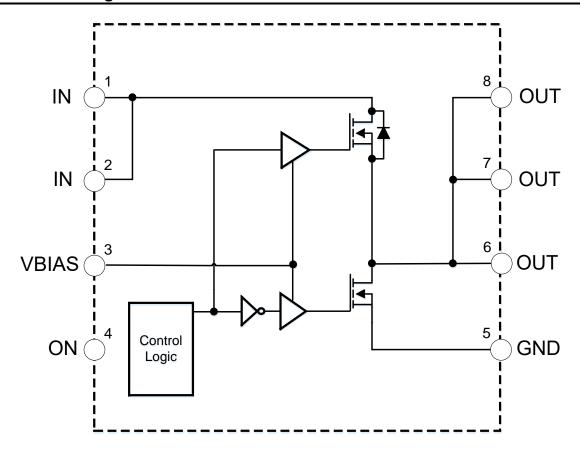




Pin Description

Pin Number	Pin Name	Pin Function
1, 2, EPAD	IN	Load Switch Input. Bypass capacitor is recommended to minimize input-voltage dip.
3	VBIAS	Bias Voltage. Power-supply input for the device.
4	ON	Enable Input. Load switch is on when ON is pulled high. Load switch is off when ON is pulled low. Do not leave floating.
5	GND	Ground.
6, 7, 8	OUT	Load Switch Output.

Functional Block Diagram





Absolute Maximum Rating

Parameter	Rating
Voltage from IN, ON, VBIAS, OUT to GND Pin	-0.3V to 6V
Junction Temperature (T _J)	+150°C
IMAX	12A
Storage Temperature (T _{STG})	-65°C to +150°C

Recommended Operating Ranges

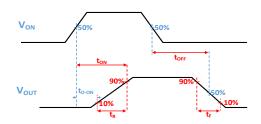
Parameter	Rating
Supply Voltage (VBIAS)	3.2V to 5.5V
Input Voltage (V _{IN})	0.8V to V _{BIAS} - 1.5V
Ambient Temperature (T _A)	-40°C to +85°C
Package Thermal Resistance (θ _{JC})	8°C/W
Package Thermal Resistance (θ _{JA})	60°C/W

Electrical Characteristics (TA = +25°C, VBIAS = 5V, VIN = 1.05V, unless otherwise specified.)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit			
VIN	IN Supply Voltage	Von = 5V	0.8	1.05	VBIAS - 1.5	V			
VBIAS	VBIAS Supply Voltage	_	3.2	5	5.5	V			
ΙD	Maximum Continuous Current	Von = 5V	_	6	_	Α			
IPLS	Maximum Pulsed Switch Current	VIN = VON = 5V Pulse < 300µs, 2% Duty Cycle	_	9	_	Α			
Iq	Quiescent Supply Current of VBIAS	IOUT = 0V, VON = 5V	_	28	_	μΑ			
loff	VBIAS Shutdown Supply Current	Von = 0V, Vout = 0V	_	_	2	μΑ			
IINOFF	IN Shutdown Supply Current	Von = 0V, Vout = 0V	_	_	2	μΑ			
I _{ON}	ON Leakage Current	V _{ON} = 5V	_	_	1	μΑ			
Vonh	ON High-Level Voltage	_	1.2	_	_	V			
Vonl	ON Low-Level Voltage	_	_	_	0.5	V			
Switching (Switching ON Resistance								
Pou	Switch ON-State Resistance	$I_{OUT} = -200$ mA, $V_{ON} = 5$ V, $V_{BIAS} = 5$ V	_	_	8	mΩ			
Ron	Switch On-State Resistance	I _{OUT} = -200mA, V _{ON} = 5V, V _{BIAS} = 3.3V	_	_	10	mΩ			
R _{PD}	Output Pulldown Resistance	I _{OUT} = 15mA, V _{ON} = 0V	_	_	200	Ω			

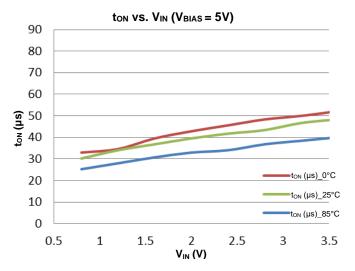
$\textbf{Switching Electrical Characteristics} \ \, (T_A = +25 ^{\circ}\text{C}, \ V_{BIAS} = V_{ON} = 5 \text{V}, \ \, C_{IN} = 1 \mu\text{F}, \ \, C_{OUT} = 0.1 \mu\text{F}, \ \, unless \ \, otherwise specified.})$

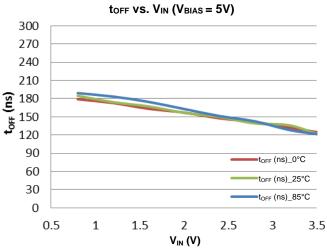
Symbol	Parameter	Min	Тур	Max	Unit					
$V_{IN} = 1.5V,$	$V_{IN} = 1.5V$, $V_{BIAS} = V_{ON} = 5V$									
ton	Turn-On Time	15	_	65						
t _{D-ON}	Turn-On Delay Time	_	20	_						
t _R	Turn-On Rise Time	_	25	_	μs					
toff	Turn-Off Time	_	0.2	_						
tF	Turn-Off Fall Time	_	0.7	_						
V _{IN} = 1.05V	Vin = 1.05V, V _{BIAS} = V _{ON} = 5V									
ton	Turn-On Time	15	_	55						
t _{D-ON}	Turn-On Delay time	_	15	_						
t _R	Turn-On Rise Time	_	20	_	μs					
toff	Turn-Off Time	_	0.2	_						
tF	Turn-Off Fall Time	_	0.7	_						

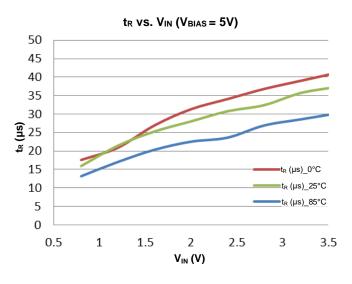


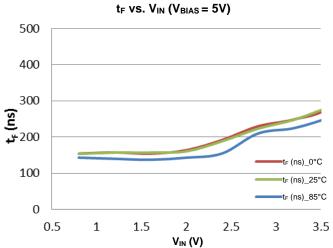


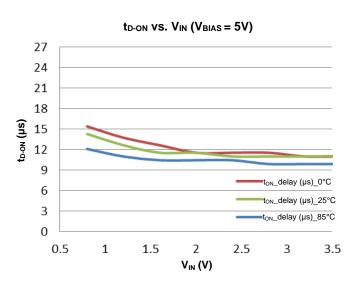
Performance Characteristics (@T_A = +25°C, unless otherwise specified.)













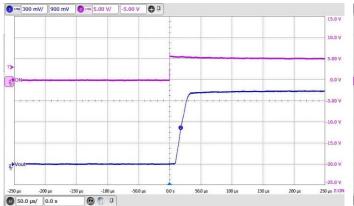
Performance Characteristics (@T_A = +25°C, unless otherwise specified.) (continued)

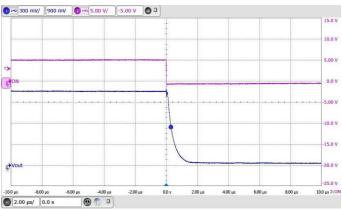
Turn-On & Turn-On Rise Time

 $V_{IN} = 1.05 V, \ V_{BIAS} = 5 V, \ C_{IN} = 1 \mu F, \ C_{OUT} = 0.1 \mu F, \ R_{OUT} = 10 \Omega$

Turn-Off & Turn-Off Fall Time

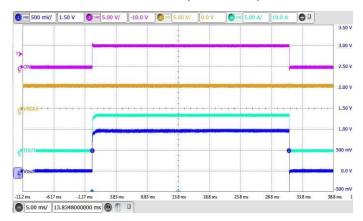
 $V_{IN} = 1.05V$, $V_{BIAS} = 5V$, $C_{IN} = 1\mu F$, $C_{OUT} = 0.1\mu F$, $R_{OUT} = 10\Omega$





Turn-On & Turn-Off at Iout = -10A

 V_{IN} = 1.05V, V_{BIAS} = 5V, C_{IN} = 1 μF , C_{OUT} = 0.1 μF , R_{OUT} = 0.1 Ω





Application Information

General Description

The DML1012ALDSQ is a single-channel, 6A load switch in an 8-pin V-DFN3030-8 (Type R) package. To reduce the voltage drop in high current rails, the device implements an ultra-low resistance n-channel MOSFET operated input-voltage range from 0.8V to 3.5V.

The device has very low leakage current during off state. This prevents downstream circuits from pulling high standby current from the supply. Integrated control logic, driver, power supply and discharge FET eliminate the needs for any external components, which reduce solution size and bill of materials (BOM) count.

Enable Control

The DML1012ALDSQ device allows for enabling the MOSFET in an active-high configuration. When the VBIAS supply pin has an adequate voltage applied and the ON pin is at logic-high level, the MOSFET is enabled. Similarly, when the ON pin is at logic-low level, the MOSFET is disabled.

Power Sequencing

The DML1012ALDSQ device will function with fixed power sequence, and the performance of output turn-on delay may vary from what is specified. To achieve the specified performance, there are two recommended power sequences:

- 1.) $V_{BIAS} \rightarrow V_{IN} \rightarrow V_{ON}$
- 2.) VIN → VBIAS → VON

Input Capacitor

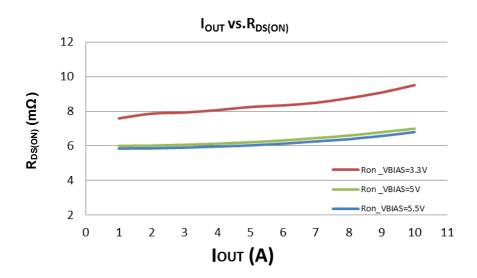
A capacitor of 10µF or higher value is recommended to be placed close to the IN pins of DML1012ALDSQ. This capacitor can reduce the voltage drop caused by the in-rush current during the turn-on transient of the load switch. A higher value capacitor can further reduce the voltage drop during high-current application.

Output Capacitor

A capacitor of $0.1\mu\text{F}$ or higher value is recommended to be placed between the OUT pins and GND pin. The switching time is affected by the capacitance. A larger capacitor makes the initial turn-on transient smoother. This capacitor must be large enough to supply a fast transient load in order to prevent the output from dropping.

VIN and VBIAS Voltage Range

For optimal on-resistance of load switch, make sure $V_{IN} \le 1.5V + V_{BIAS}$ and V_{BIAS} is within the voltage range from 3.2V to 5.5V. On-resistance of load switch will be higher if $V_{IN} + 1.5V > V_{BIAS}$. Resistance curves of a typical sample device at different $V_{BIAS} = V_{IN}$ at $I_{OUT} = -200$ mA are shown as below.





Application Information (continued)

Thermal Considerations

To ensure proper operation, the maximum junction temperature of the DML1012ALDSQ should not exceed +150°C. Several factors attribute to the junction temperate rise: load current, MOSFET on-resistance, junction-to-ambient thermal resistance, and ambient temperature. The maximum load current can be determined by:

$$I_{LOAD(MAX)} = \sqrt{\frac{T_{J(MAX)} - T_{C}}{\Theta_{JC} \times R_{DS(ON)}}}$$

Where

ILOAD(MAX) is the maximum allowable current on load (A). (6A for DML1012ALDSQ)

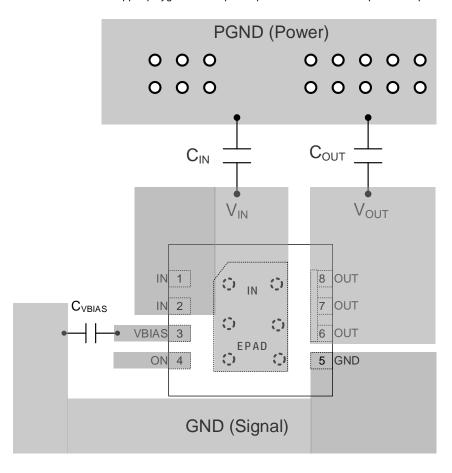
T_{J(MAX)} is the maximum allowable junction temperature.

Tc is the case temperature of the device.

θ_{JC} = junction to case thermal impedance. This parameter is highly dependent upon PCB layout.

PCB Layout Consideration

- 1. Place the input/output capacitors C_{IN} and C_{OUT} as close as possible to the IN and OUT pins.
- 2. The power traces, which are IN trace, OUT trace and GND trace, should be short, wide and directly for minimizing parasitic inductance.
- 3. Place CVBIAS capacitor near the device pin.
- 4. Connect the signal ground to the GND pin, and keep a single connection from GND pin to the power ground behind the input or output capacitors.
- 5. For better power dissipation, holes are recommended to connect to the exposed pad's landing area with a large copper polygon on the other side of the printed circuit board. The copper polygons and exposed pad shall connect to IN pin on the printed circuit board.

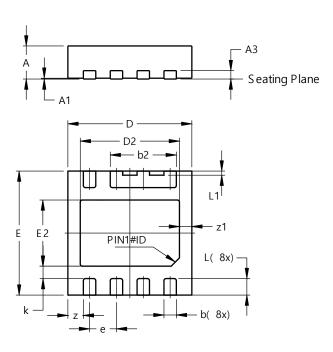




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

V-DFN3030-8 (Type R)

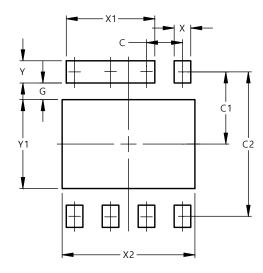


	V-DFN3030-8								
(Type R)									
Dim	Dim Min Max Typ								
Α	0.77	0.83	0.80						
A1	0.00	0.05	0.03						
А3	-	-	0.203						
b	0.25	0.35	0.30						
b2	1.55	1.65	1.60						
D	D 2.95 3.05		3.00						
D2	2.30	2.50	2.40						
E	2.95	3.05	3.00						
E2	1.50	1.70	1.60						
е		0.65 B	SC						
k			0.30						
١	0.35	0.45	0.40						
L1	0.05	0.15	0.10						
Z			0.375						
z1			0.30						
All	Dimen	sions	in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

V-DFN3030-8 (Type R)

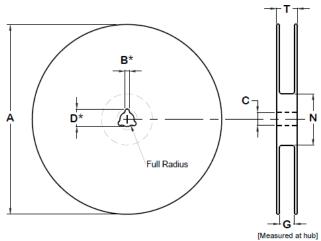


Dimensions	Value (in mm)
С	0.65
C1	1.30
C2	2.60
G	0.30
Х	0.30
X1	1.60
X2	2.40
Y	0.40
V1	1.60



Surface-Mount Reel Specifications (All dimensions in mm.)

Please see https://www.diodes.com/assets/Packaging-Support-Docs/AP02007.pdf for the latest version.



* Drive spokes optional. If used, dimensions with asterisks apply.

DML1012ALDSQ-7A

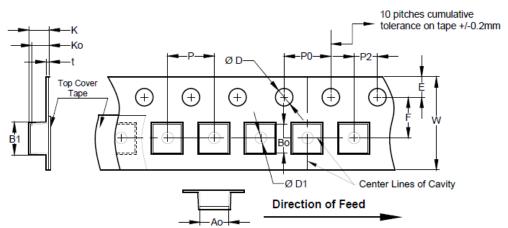
Tape Size	A Max	B* Max	С	D* Max	N Min	G	T Max
12mm	178 ±2	2.0 _{+0.5}	13 _{+0.5}	20.5 ±0.2	55 ±5	12.4 _{+2.0} -0.0	18.4

DML1012ALDSQ-13

Tape Size	A Max	B* Max	С	D* Max	N Min	G	T Max
12mm	330 ±2	2.0 _{+0.5}	13 _{+0.5} -0.2	20.5 ±0.2	100 ±2	12.4 _{+2.0} -0.0	18.4

Embossed Carrier Tape Specifications

Please see https://www.diodes.com/assets/Packaging-Support-Docs/AP02007.pdf for the latest version.



8, 12, 16, 24mm EMBOSSED TAPE DIMENSIONS IN mm								
Tape Width	D	E	Po	tmax	A _o B _o K _o			
8, 12, 16, 24mm	1.50 +0.10 -0.0	1.75 ± 0.10	4.0 ± 0.10	0.400	(Note 5)	Constant Dimensions		

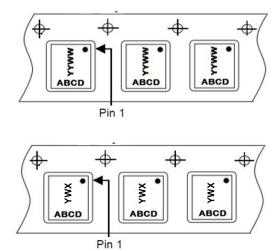
Tape Width	B1 max	D1 min	F	K max	P2	W	Р
12mm	8.2	1.5	5.5 ± 0.05	4.5	2.0 ± 0.05	12.0 ± 0.30	8.0 ± 0.10

Note: 5. Ao Bo Ko are determined by component size.



Tape Orientation

 $Please see \ https://www.diodes.com/assets/Packaging-Support-Docs/AP02007.pdf \ for \ the \ latest \ version.$





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